

MOS FIELD EFFECT TRANSISTOR 2SK3642

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3642 is N-channel MOS FET device that features a low on-state resistance and excellent switching characteristics, and designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

ORDERING INFORMATION

PART NUMBER	PACKAGE			
2SK3642-ZK	TO-252 (MP-3ZK)			

FEATURES

Low on-state resistance

 $R_{DS(on)1}$ = 9.5 m Ω MAX. (Vgs = 10 V, ID = 32 A) $R_{DS(on)2}$ = 16 m Ω MAX. (Vgs = 4.5 V, ID = 18 A)

- Low Ciss: Ciss = 1100 pF TYP.
- · Built-in gate protection diode

(TO-252)



ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (VGS = 0 V)	VDSS	30	V
Gate to Source Voltage (Vps = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±64	Α
Drain Current (pulse) Note1	D(pulse)	±190	Α
Total Power Dissipation (Tc = 25°C)	P _{T1}	36	W
Total Power Dissipation	P _{T2}	1.0	W
Channel Temperature	T_ch	150	°C
Storage Temperature	T_{stg}	-55 to + 150	°C
Single Avalanche Current Note2	las	25	Α
Single Avalanche Energy Note2	Eas	62	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Starting T_{ch} = 25°C, V_{DD} = 15 V, R_G = 25 Ω , L = 100 μ H, V_{GS} = 20 \rightarrow 0 V

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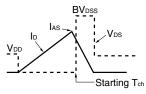
ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 30 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	Igss	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μΑ
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.5		2.5	V
Forward Transfer Admittance Note	yfs	V _{DS} = 10 V, I _D = 32 A	13	26		S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = 10 V, I _D = 32 A		7.6	9.5	mΩ
	RDS(on)2	V _{GS} = 4.5 V, I _D = 18 A		10.8	16	mΩ
Input Capacitance	Ciss	V _{DS} = 10 V		1100		pF
Output Capacitance	Coss	V _{GS} = 0 V		410		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		150		pF
Turn-on Delay Time	t d(on)	V _{DD} = 15 V, I _D = 32 A		9.6		ns
Rise Time	tr	V _{GS} = 10 V		5.1		ns
Turn-off Delay Time	td(off)	R _G = 10 Ω		38		ns
Fall Time	tf			10		ns
Total Gate Charge	Q _G	V _{DD} = 24 V		23		nC
Gate to Source Charge	Qgs	V _{GS} = 10 V		4.3		nC
Gate to Drain Charge	Q _{GD}	I _D = 64 A		6		nC
Body Diode Forward Voltage Note	V _{F(S-D)}	I _F = 64 A, V _{GS} = 0 V		1.0		V
Reverse Recovery Time	trr	I _F = 64 A, V _{GS} = 0 V		31		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		25		nC

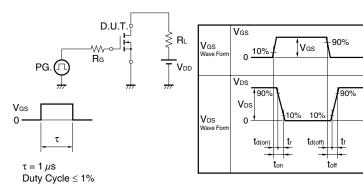
Note Pulsed: PW \leq 350 μ s, Duty Cycle \leq 2%

TEST CIRCUIT 1 AVALANCHE CAPABILITY

$V_{GS} = 20 \rightarrow 0 \text{ V}$ $PG. \bigcirc PG. \bigcirc PG. \bigcirc PG. \bigcirc PV_{DD}$ PV_{DD} PV_{DD} PV_{DD}



TEST CIRCUIT 2 SWITCHING TIME

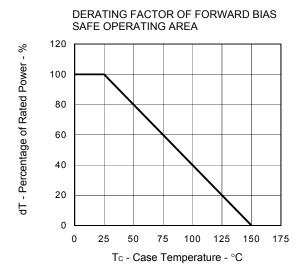


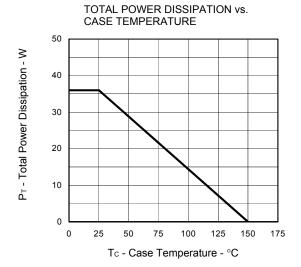
TEST CIRCUIT 3 GATE CHARGE

$$\begin{array}{c|c} D.U.T. \\ I_G = 2 \text{ mA} \\ \hline \\ VOID \\ \end{array}$$

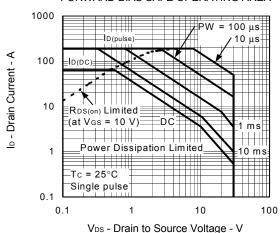


TYPICAL CHARACTERISTICS (TA = 25°C)

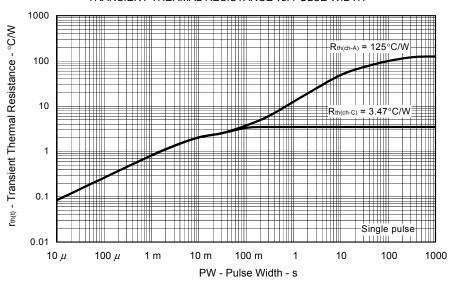




FORWARD BIAS SAFE OPERATING AREA

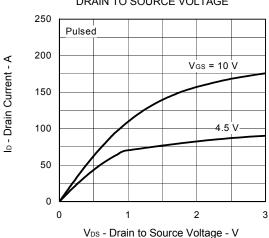


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

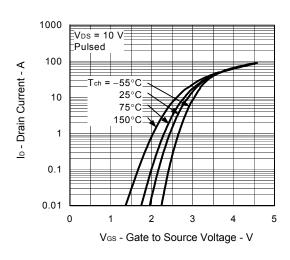




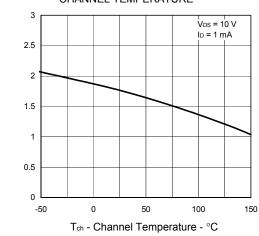
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



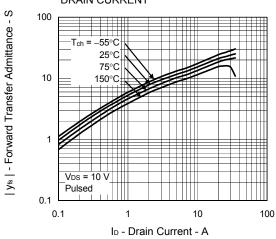
FORWARD TRANSFER CHARACTERISTICS



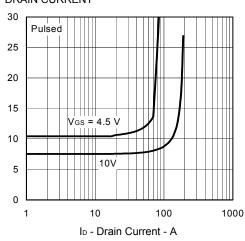
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



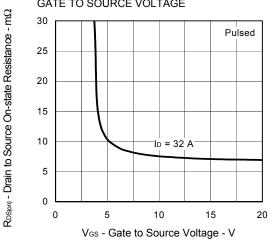
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

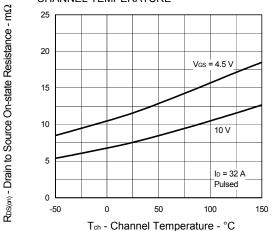


R_{DS(on)} - Drain to Source On-state Resistance - mΩ

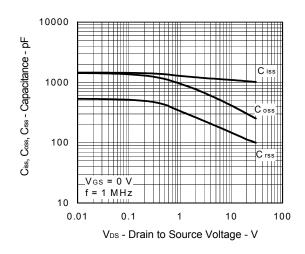
VGS(off) - Gate Cut-off Voltage - V



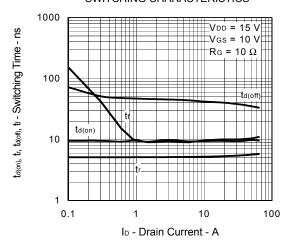
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



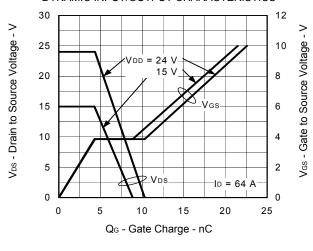
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



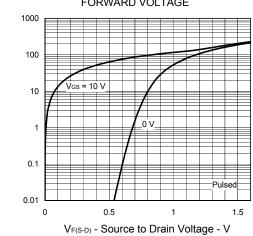
SWITCHING CHARACTERISTICS



DYNAMIC INPUT/OUTPUT CHARACTERISTICS

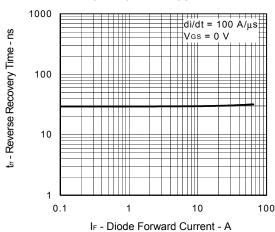


SOURCE TO DRAIN DIODE FORWARD VOLTAGE



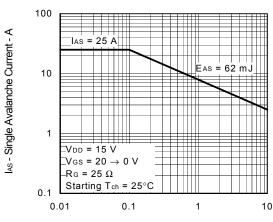
IF - Diode Forward Current - A

REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



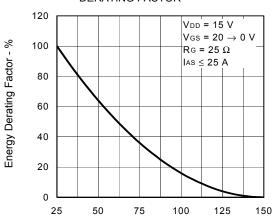


SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



L - Inductive Load - mH

SINGLE AVALANCHE ENERGY DERATING FACTOR

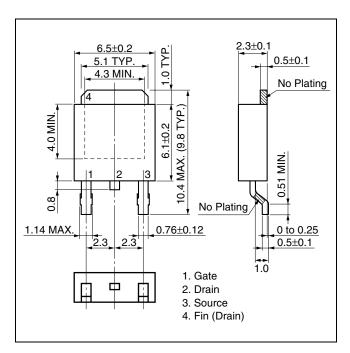


Starting Tch - Starting Channel Temperature - °C

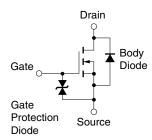


★ PACKAGE DRAWING (Unit: mm)

TO-252 (MP-3ZK)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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